TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20150602000
Assembly Site move from Amkor K1 to TI Melaka for DP83846AVHG/NOPB Device
Change Notification / Sample Request

Dear Customer:

Amkor K1 (Korea) is closing its facility by 2015. This product change announcement is to support transfer of products in the TQFP package to alternate sites. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days to ensure you can complete your evaluation and product transfer to the new site can be completed prior to the HIJI site closure.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

PCN# 20150602000
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20150602000	**PCN Date:**	06/05/2015
Title:	Assembly Site move from Amkor K1 to TI Melaka for DP83846AVHG/NOPB Device		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	09/05/2015	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Assembly Site move from Amkor K1 to TI Melaka for Select Device. No material differences between sites.

Reason for Change:

Closure of the Amkor K1 assembly facility. Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

Sample Product Shipping Label (not actual product label)

Group 1: Assembly Site

Amkor K1	Assembly Site Origin (22L)	ASO: AMN
TI Melaka (TIEMA)	Assembly Site Origin (22L)	ASO: GNZ

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: AMKOR K1 =7, TIEMA = 1

Product Affected Group:

DP83846AVHG/NOPB

Qualification Report

Amkor K1 Closure and L/TQFP transfer to TIEMA

Product Description

Part Number	Process	Package / # Leads	Moisture Sensitivity Level
DP83846AVHC2WQ Product Data	CMOS7	LQFP 80 Leads	3
DP83640TVVX Product Data	CMOS9T	LQFP 48 Leads	3
LP5221TM QBS Process Data	CMOS7	WCP 20Bumps	1
DP83851DVN QBS Package Data	CMOS7	LQFP 144 Leads	3
DP83848VV (QBS Product Family Data)	CMOS9T	LQFP 48 Leads	3

- QBS: Qual By Similarity – Reliability data from similar product family, wafer fab process and package may be used to support qualification

Qualification Results

Data Displayed as: Total failed / Total sample size

Test Methods	Conditions	Product Data DP83846AVHC2WQ	Product Data DP83640TVVX	Process QBS Data LP5521TM Lot1,2,3	Product Family Data DP83848VV	QBS Package Data DP83851DVN Lot1,2,3
ELFR JESD22-A108	125°C (48hrs)			0/231	0/805	0/800
HTOL JESD22-A108	125°C (408hrs)		0/77	0/1145	0/240	0/77
ACLV JESD22-A102	121°C, 100% 15PSI (96hrs)					0/60
HAST JESD22-A101	130°C, 85% 13.3PSI (96hrs)				0/80	0/77
TMCL JESD22-A104	-65°C to 150°C (500cyc)					0/120
HTSL JESD22-A103	150°C (1000hrs)					0/45
ESDH JESD22-A114	1.5kOhm, 100pF Room Temp (2000V)	0/3	0/3		0/3	
ESDC JESD22-C101	JESD22-C101 (1000V)	0/3	0/3		0/3	
ESDM JESD22-A115	JESD22-A115 (300V)	0/3	0/3		0/3	
LUPS	Over Voltage and Current Test (28°C / 85°C)	0/6	0/6		0/6	

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com